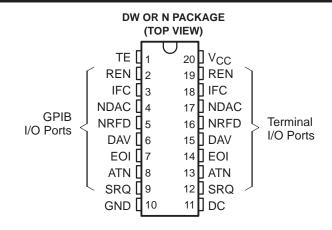
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- Suitable for IEEE Standard 488-1978 (GPIB)
- 8-Channel Bidirectional Transceivers
- Designed to Implement Control Bus Interface
- Designed for Single Controller
- High-Speed Advanced Low-Power Schottky Circuitry
- Low Power Dissipation . . . 46 mW Max Per Channel
- Fast Propagation Times . . . 20 ns Max
- High-Impedance pnp Inputs
- Receiver Hysteresis . . . 650 mV Typ
- Bus-Terminating Resistors Provided on Driver Outputs
- No Loading of Bus When Device Is Powered Down (V<sub>CC</sub> = 0)
- Power-Up/Power-Down Protection (Glitch Free)

#### description/ordering information

The SN75ALS161 eight-channel general-purpose interface bus transceivers are high-speed, advanced low-power Schottky-process devices designed to provide the



#### **CHANNEL-IDENTIFICATION TABLE**

NAME	IDENTITY	CLASS
DC	Direction Control	Control
TE	Talk Enable	Control
ATN	Attention	
SRQ	Service Request	
REN	Remote Enable	Bus
IFC	Interface Clear	Management
EOI	End or Identify	
DAV	Data Valid	5.
NDAC	Not Data Accepted	Data Transfer
NRFD	Not Ready for Data	Hansiei

bus-management and data-transfer signals between operating units of a single-controller instrumentation system. When combined with the SN75ALS160 octal bus transceivers, this device provides a complete 16-wire interface for the IEEE 488 bus.

The SN75ALS161 device features eight driver-receiver pairs connected in a front-to-back configuration to form input/output (I/O) ports at both the bus and terminal sides. The direction of data through these driver-receiver pairs is determined by the direction-control (DC) and talk-enable (TE) signals.

The driver outputs general-purpose interface bus (GPIB I/O ports) feature active bus-terminating resistor circuits designed to provide a high impedance to the bus when  $V_{CC} = 0$ . The drivers are designed to handle sink-current loads up to 48 mA. Each receiver features pnp transistor inputs for high input impedance and hysteresis of 400 mV on the commercial part, and 250 mV on the military part, minimum, for increased noise immunity. All receivers have 3-state outputs, to present a high impedance to the terminal when disabled.

The SN75ALS161 is characterized for operation from 0°C to 70°C.

#### ORDERING INFORMATION

TA	PACK	(AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP (N)	Tube of 20	SN75ALS161N	SN75ALS161N
0°C to 70°C	0010 (011)	Tube of 25	SN75ALS161DW	7541 0404
	SOIC (DW)	Reel of 2000	SN75ALS161DWR	75ALS161

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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## FUNCTION TABLE RECEIVE/TRANSMIT

C	ONTRO	LS	BUS	-MANA	SEMENT	CHANN	IELS	DATA-TRANSFER CHANNELS			
DC	TE	ATN†	ATN <sup>†</sup> SRQ REN IFC (CONTROLLED BY DC)				EOI	DAV (CON	NDAC TROLLED E	NRFD BY TE)	
Н	Н	Н	,	_	,	,	Т	-	_	-	
Н	Н	L	R	ı	T R	R	R	ı	R	R	
L	L	Н	_		_	_	R	-	-	_	
L	L	L	l '	R	ı	1	Т	R	ı	ı	
Н	L	Х	R	Т	R	R	R	R	Т	Т	
L	Н	Χ	Т	R	Т	Т	T	Т	R	R	

H = high level, L = low level, R = receive, T = transmit, X = irrelevant

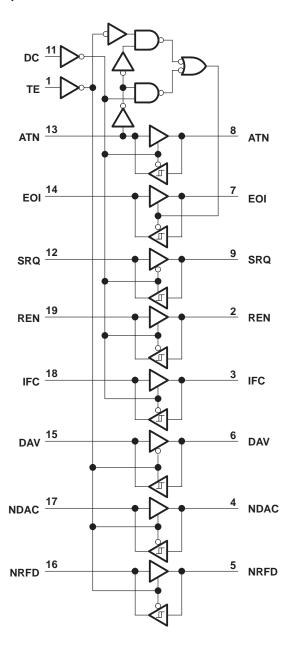
Direction of data transmission is from the terminal side to the bus side, and the direction of data receiving is from the bus side to the terminal side.

Data transfer is noninverting in both directions.



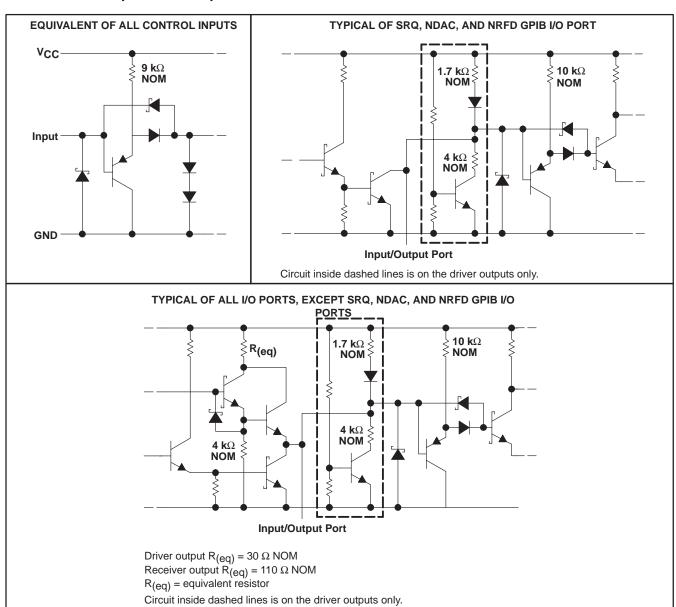
<sup>&</sup>lt;sup>†</sup> ATN is a normal transceiver channel that functions additionally as an internal direction control or talk enable for EOI whenever the DC and TE inputs are in the same state. When DC and TE are in opposite states, the ATN channel functions as an independent transceiver only.

## logic diagram (positive logic)



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#### schematics of inputs and outputs



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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub> (see Note 1)		7 V
Input voltage, V <sub>I</sub>		
Low-level driver output current, I <sub>OL</sub>		) mA
Package thermal impedance, $\theta_{JA}$ (see Notes 2 and 3):	: DW package 58°	C/W
	N package 69°	C/W
Operating virtual junction temperature, T <sub>J</sub>		50°C
Storage temperature range, T <sub>sto</sub>	–65°C to 15	50°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values are with respect to network ground terminal.
  - 2. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions

			MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.75	5	5.25	V
VIH	High-level input voltage		2			V
VIL	Low-level input voltage				8.0	V
	I Park Town London London	Bus ports with pullups active			- 5.2	mA
	High-level output current	Terminal ports			- 800	μΑ
		Bus ports			48	
IOL	Low-level output current	h-level output current Terminal ports  Bus ports Terminal ports  Terminal ports			16	mA
TA	Operating free-air temperature		0		70	°C

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#### electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER		TES	T CONDITION:	s†	MIN	TYP‡	MAX	UNIT
٧ıK	Input clamp voltage		$I_{I} = -18 \text{ mA}$				-0.8	-1.5	V
V <sub>hys</sub>	Hysteresis voltage (V <sub>IT+</sub> – V <sub>IT-</sub> )	Bus				0.4	0.65		V
		Terminal	I <sub>OH</sub> = - 800 μA,	V <sub>CC</sub> = MIN	T <sub>A</sub> = 25°C and MAX	2.7	3.5		
., 8	LPak lavel extend value				$T_A = MIN$	2.7	3.5		.,
V <sub>OH</sub> §	High-level output voltage	Bus	I <sub>OH</sub> = – 5.2 mA,	V <sub>CC</sub> = MIN	T <sub>A</sub> = 25°C and MAX	2.2			V
					$T_A = MIN$	2.2			
V	Low-level output voltage	Terminal	$I_{OL} = 16 \text{ mA},$	$V_{CC} = MIN$			0.3	0.5	V
VOL	Low-level output voltage	Bus	$I_{OL} = 48 \text{ mA},$	$OL = 48 \text{ mA}, \qquad V_{CC} = \text{MIN}$			0.35	0.5	V
lį	Input current at maximum input voltage	Terminal	V <sub>I</sub> = 5.5 V,	$V_{CC} = MAX$			0.2	100	μΑ
lн	High-level input current	Terminal and control inputs	V <sub>I</sub> = 2.7 V,	V <sub>CC</sub> = MAX			0.1	20	μΑ
			$I_{I(bus)} = 0$			2.5	3	3.7	
V <sub>I/O</sub>	Voltage at GPIB I/O port		$I_{I(bus)} = 0$			2.5	3	3.7	V
			$I_{I(bus)} = -12 \text{ mA}$	l				-1.5	
I <sub>IL</sub>	Low-level input current	Terminal and control inputs	V <sub>I</sub> = 0.5 V,	V <sub>CC</sub> = MAX			-10	-100	μΑ
			$V_{I(bus)} = -1.5 V$	to 0.4 V		-1.3			
			$V_{I(bus)} = 0.4 V t$	o 2.5 V		0		-3.2	
I <sub>I/O</sub>	Current into GPIB I/O port	Power on	$V_{I(bus)} = 2.5 V t$	o 3.7 V				2.5 -3.2	mA
	·		$V_{I(bus)} = 3.7 V t$	o 5 V		0		2.5	
			$V_{I(bus)} = 5 V to$	5.5 V		0.7		2.5	
		Power off	VCC = 0	$V_{I(bus)} = 0 to$	o 2.5 V			40	μΑ
8	Short-circuit output current	Terminal	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\			-15	-35	-75	mA
los§	Short-Groun output current	Bus	V <sub>CC</sub> = MAX			-25	-50	-125	IIIA
ICC	Supply current		No load,	TE and DC lo			55	75	mA
C <sub>I/O</sub>	GPIB I/O port capacitance		$V_{CC} = 0 \text{ to 5 V},$	$V_{I/O} = 0 \text{ to } 2$	V, f = 1 MHz		30		pF

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

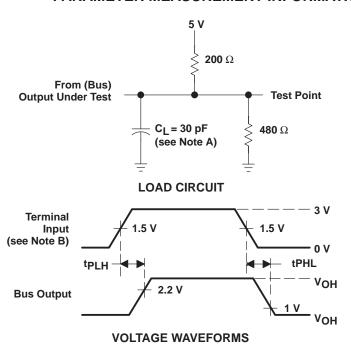
<sup>‡</sup> All typical values are at  $V_{CC} = 5$  V,  $T_A = 25^{\circ}$ C. §  $V_{OH}$  and  $I_{OS}$  apply to 3-state outputs only.

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## switching characteristics over recommended operating free-air temperature range, $V_{CC} = 5 \text{ V}$

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP <sup>†</sup>	MAX	UNIT	
<sup>t</sup> PLH	Propagation delay time, low- to high-level output	Taminal Bus		C <sub>I</sub> = 30 pF,		10	20	ns	
<sup>t</sup> PHL	Propagation delay time, high- to low-level output	Terminal	Bus	See Figure 1		12	20		
tPLH	Propagation delay time, low- to high-level output		<b>-</b>	C <sub>L</sub> = 30 pF,		5	10		
tPHL	Propagation delay time, high- to low-level output	Bus	Terminal	See Figure 2		7	14	ns	
<sup>t</sup> PZH	Output enable time to high level						30		
<sup>t</sup> PHZ	Output disable time from high level	Bus (ATN, EOI, C <sub>I</sub> = 15 pF,				20			
tPZL	Output enable time to low level	TE OF DC	TE or DC REN, IFC, and DAV)				45	ns	
t <sub>PLZ</sub>	Output disable time from low level		,				20		
<sup>t</sup> PZH	Output enable time to high level						30		
<sup>t</sup> PHZ	Output disable time from high level	TE or DC Terminal C		C <sub>L</sub> = 15 pF,			25	20	
tpzL	Output enable time to low level	TEULDO	remina	See Figure 4			30	ns	
tPLZ	Output disable time from low level						25		

<sup>†</sup> All typical values are at  $T_A = 25$ °C.

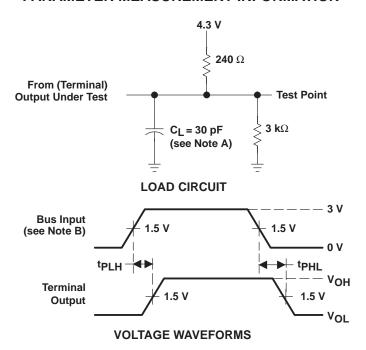


NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_{\Gamma} \leq$  6 ns,  $t_{\tilde{f}} \leq$  6 ns,  $Z_{\tilde{O}} = 50 \ \Omega$ .

Figure 1. Terminal-to-Bus Load Circuit and Voltage Waveforms

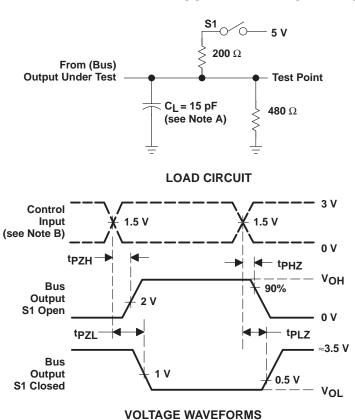




NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_{\Gamma} \leq$  6 ns,  $t_{\Gamma} \leq$  7 ns,  $t_{\Gamma} \leq$  8 ns,  $t_{\Gamma} \leq$  8 ns,  $t_{\Gamma} \leq$  9 ns,  $t_{\Gamma} \leq$ 

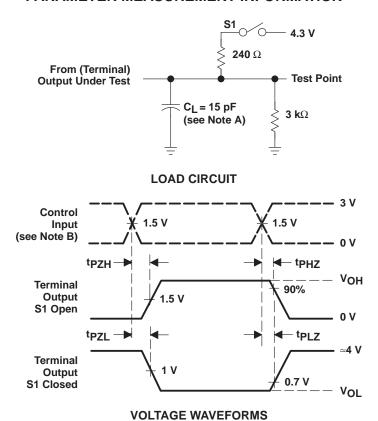
Figure 2. Bus-to-Terminal Load Circuit and Voltage Waveforms



NOTES: A.  $C_L$  includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_r \leq$  6 ns,  $t_f \leq$  6 ns,  $Z_O = 50 \Omega$ .

Figure 3. Bus Load Circuit and Voltage Waveforms

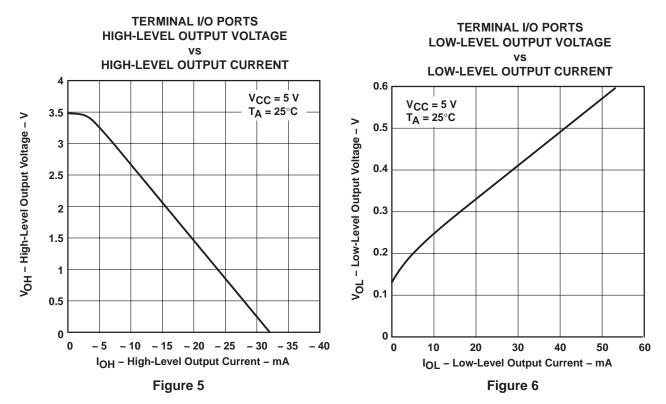


NOTES: A.  $C_L$  includes probe and jig capacitance.

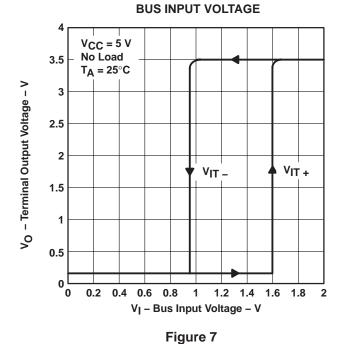
B. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_{\Gamma} \leq$  6 ns,  $t_{f} \leq$  6 ns,  $t_{Q} =$  50  $\Omega$ .

Figure 4. Terminal Load Circuit and Voltage Waveforms

#### TYPICAL CHARACTERISTICS<sup>†</sup>



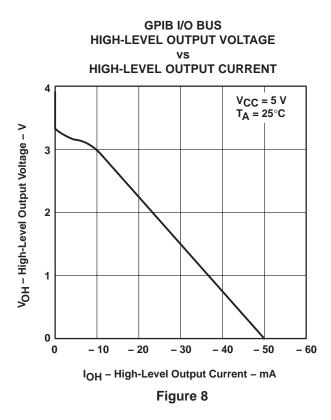
## TERMINAL OUTPUT VOLTAGE vs

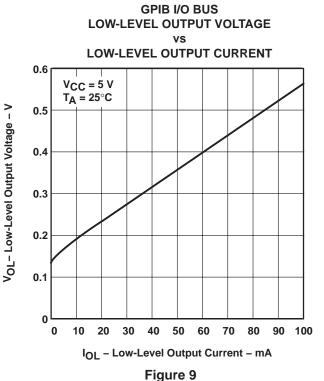


† Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.



#### TYPICAL CHARACTERISTICS<sup>†</sup>





**GPIB I/O BUS** 

BUS OUTPUT VOLTAGE
vs
TERMINAL INPUT VOLTAGE

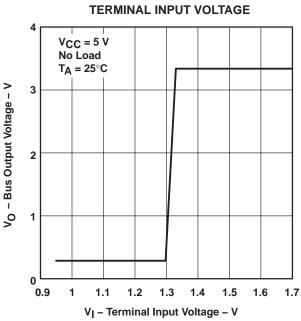
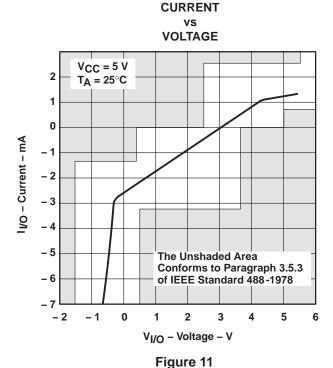


Figure 10



† Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.



#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN75ALS161DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS161DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS161DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS161DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS161DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS161DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS161N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS161NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### OTHER QUALIFIED VERSIONS OF SN75ALS161:

Military: SN55ALS161

NOTE: Qualified Version Definitions:



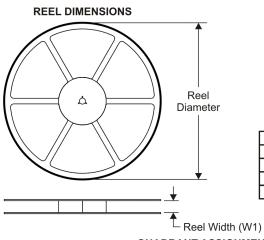
## **PACKAGE OPTION ADDENDUM**

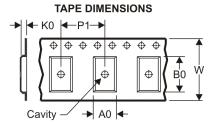
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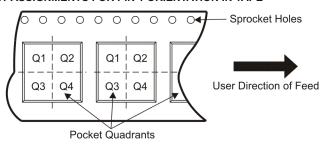
#### TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS161DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.1	2.65	12.0	24.0	Q1





#### \*All dimensions are nominal

ĺ	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
	SN75ALS161DWR	SOIC	DW	20	2000	346.0	346.0	41.0

## DW (R-PDSO-G20)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



## N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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